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# **Product Change Notification**

Change Notification #:	118749-00
Change Title:	Select Intel® SSD D7-P5510 Series SKUs,
	PCN 118749-00, Product Material,
	Add new IC as 2nd Source
Date of Publication:	December 09, 2021

#### **Key Characteristics of the Change:**

Product Material

#### **Forecasted Key Milestones:**

D	ate Customer Must be Ready to Receive Post-Conversion Material	February 09, 2022

#### **Description of Change to the Customer:**

The Intel SKUs listed in the products affected table will have the following changes.

• All SKUs adding the following alternate components:

Туре	Use Case	Current Component(s)	Alternate Component(s)
Circuit Protection Diode	3.3V Aux	Diodes, Inc./ON Semi (G24376-001)	Nexperia (M59419-001)
MOSFET	Vcap Switch	Diodes, Inc. (J53658-001)	Toshiba (M59118-001)
MOSFET	SMBus LVL Shifter	Diodes, Inc. (K41819-001) Nexperia (H75826-001)	ON Semi (G50657-001)
Voltage Regulator	N/A	MPS (J78028-001)	MPS (J78028-002) **

\*\*The alternate MPS voltage regulator (IPN: J78028-002) is a document-up version of the current MPS V-Reg (IPN: J78028-001); the only spec difference is the reverse current spec, which does not affect the component in its current use case in Intel® SSDs. Per NPSG policy, a new IPN is required for the "rev-up" part and the part is included in this PCN.

#### **Customer Impact of Change and Recommended Action:**

Intel anticipates no impact to customers.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

### **Products Affected/Intel Ordering Codes:**

Marketing Name	Product Code	MM#
Intel® SSD D7-P5510 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack OPAL	SSDPF2KX038TZOS	99A5CZ
Intel® SSD D7-P5510 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack OPAL	SSDPF2KX076TZOS	99A5D1
Intel® SSD D7-P5510 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack	SSDPF2KX038TZ01	99A5DP
Intel® SSD D7-P5510 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic Single Pack	SSDPF2KX076TZ01	99A5DR
Intel® SSD D7-P5510 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic 50 Pack	SSDPF2KX038TZ	99AJR9
Intel® SSD D7-P5510 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D4, TLC) Generic 50 Pack	SSDPF2KX076TZ	99AJRA

## **PCN Revision History:**

Date of Revision:	<b>Revision Number:</b>	Reason:
December 09, 2021	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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